Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP ProCurve Access Controller 720wl (J8153A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	9
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	On power supply PCA	5
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screwdriver	P0 and P1
Pozidriv Screwdriver	1Pt
Flat Screwdriver	1/8"
Wire stripper/cutter	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove screws securing top cover using Phillips screw driver P1. Remove cover
2. Disconnect 40 pin flat cable from main PCA to Hard Drive
3. Unscrew and remove 2 philipps screws on left side of chassis securing Hard Disk Assy
4. Unscrew and remove 2 Pozidriv screws inside the chassis securing Hard Disk Assy (use 1Pt screwdriver)
5. Disconnect flat cable and power cable from Compactflash assy.
6. Remove top hard disk bracket containing small PCA and Compactflash .
7. Remove flash card PCA assembly by removing 4 philipps screws attaching PCA to bracket (Use P1 screw)
8. Unscrew and remove 1 Pozidriv screw inside chassis securing the front bracket that secures Hard Disk to Chassis
9. Unscrew 2 philipps screws attaching Power Supply to rear Chassis
10. Cut off 2 cable ties attaching power supply cable bundle to right hand side of chassis
11. Disconnect from main PCA a 20-pin connector and a 4-pin connector from power supply
12. Pull-up and remove Power Supply.
13. Remove and disassemble Power Supply P/N 9PA3501303 by first removing 1 Pozidriv screw (1Pt) attaching rear power supply bracket to bottom main chassis and 2 Phillips (P1) screws to rear chassis panel. Pull out power supply from main chassis
14. Unscrew 5 Pozidriv screws (1Pt) that attach power supply top cover to power supply sheet metal. Pull out cover.
15. Remove small bracket from rear power supply chassis by unscrewing 2 philipps screws (use P1 screwdriver).
16. Using a wire stripper/cutter cut off all cables and bundles that goes into power supply
17. Remove power supply fans. Remove 4 philipps screws (using P1 Phillips screwdriver) attaching small fan to power supply chassis. Repeat process for each fan. Cut off fan wires and remove fans.
18. Remove 1 Pozidriv screw that holds small PCA (2cm x 1.5 cm) located at the rear power supply chassis. Cut off cables and remove PCA.
19. Remove 4 Pozidriv screws holding power supply board to power supply metal box. Pull out board
20. Remove 5 large caps from PCA
21. Disconnect rear fan cables from main PCA. Repeat process for each fan.
22. Remove 4 philipps screws securing fans to rear chassis. Repeat process for each fan. Remove fans
23. Disconnect or cut off all remaining cables connected to the PCA motherboard
24. Disconnect small cable from Heat Sink fan to motherboard
25. Remove large Heat sink by first moving the 2 grey levers 180 degrees each in their opposing direction until top fan assembly become loose, using a flat screwdriver (1/8') pry-off each plastic anchor end until fan assembly comes off. Remove Heat sink
26. Remove PCI riser board attached to mother board with a socket
27. Remove RAM memory boards from sockets
28. Remove battery from main mother board
29. Disconnect cable from LCD assembly. Using Phillips P0 screwdriver remove 4 screws attaching LCD assembly to the front sheet metal. Remove LCD assembly.
30. Remove 9 Pozidriv screws attaching motherboard to chassis. Remove board
31.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).